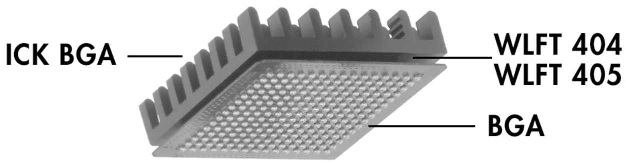
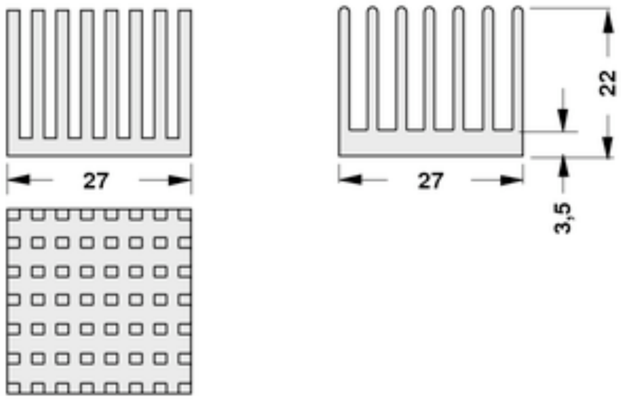
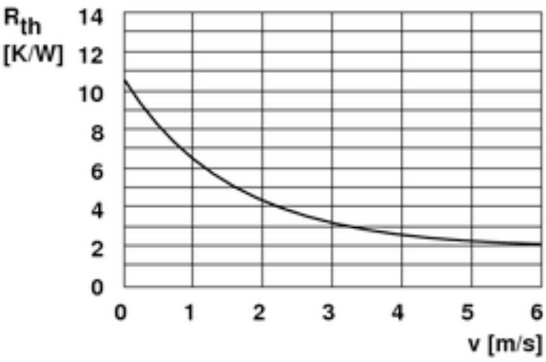
Heatsinks for BGAs / **ICK BGA 27 x 27 x 22**







27 x 27 x 22 mm, for IC design BGA and others

Parameters of article ICK BGA 27 x 27 x 22

R_{th} [K/W]	13.5
dissipation loss [W]	9.5
mounting method	therm. conductive foil / therm. cond. adhesive
socket	universal
suitable for processor type	universal
width [mm]	27
heigth [mm]	14
plate thickness [mm]	2.5
length on stock [mm]	27
surface treatment	black anodised

Accessories/ related articles

Thermally conductive foil both sides adhesive / **WLFT 404 27 x 27**
Thermally conductive foil both sides adhesive / **WLFT 405 27 x 27**

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